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1	8739	257/704 257/706 257/707 257/713 257/718 257/720 257/675 257/728 257/779 257/783	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/09/07 15:35
2	2981	(257/704 257/706 257/707 257/713 257/718 257/720 257/675 257/728 257/779 257/783) and ((heat thermal) NEAR (spreader dissipat\$3))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/09/07 16:25
3	2164	((257/704 257/706 257/707 257/713 257/718 257/720 257/675 257/728 257/779 257/783) and ((heat thermal) NEAR (spreader dissipat\$3))) and (die chip wafer)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/09/07 16:25
4	37	((257/704 257/706 257/707 257/713 257/718 257/720 257/675 257/728 257/779 257/783) and ((heat thermal) NEAR (spreader dissipat\$3))) and (die chip wafer) and (adhesion NEAR (layer film))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/09/07 15:52
5	2	("4561011") or ("6091603").PN.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/09/07 15:52
6	722	((257/704 257/706 257/707 257/713 257/718 257/720 257/675 257/728 257/779 257/783) and ((heat thermal) NEAR (spreader dissipat\$3))) and (die chip wafer) NEAR surface)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/09/07 16:26
7	17	((257/704 257/706 257/707 257/713 257/718 257/720 257/675 257/728 257/779 257/783) and ((heat thermal) NEAR (spreader dissipat\$3))) and (die chip wafer) NEAR surface)) and (solder-wet\$4 (solder NEAR wet\$4))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/09/07 16:26
8	1		USPAT	2002/09/07 16:03
9	1		USPAT	2002/09/07 16:03
10	1		USPAT	2002/09/07 16:04
11	1		USPAT	2002/09/07 16:04
12	1		USPAT	2002/09/07 16:05
13	1		USPAT	2002/09/07 16:05
14	1		USPAT	2002/09/07 16:06
15	1		USPAT	2002/09/07 16:06
16	1		USPAT	2002/09/07 16:07
17	1		USPAT	2002/09/07 16:08
18	1		USPAT	2002/09/07 16:08
19	1		USPAT	2002/09/07 16:08
20	1		USPAT	2002/09/07 16:09
21	1		USPAT	2002/09/07 16:09
22	1		USPAT	2002/09/07 16:09
23	1		USPAT	2002/09/07 16:09
24	1		USPAT	2002/09/07 16:10
25	1		USPAT	2002/09/07 16:10
26	1		USPAT	2002/09/07 16:10
27	1		USPAT	2002/09/07 16:10
28	1		USPAT	2002/09/07 16:10
29	1		USPAT	2002/09/07 16:10
30	1		USPAT	2002/09/07 16:11
31	1		USPAT	2002/09/07 16:12
32	1		USPAT	2002/09/07 16:13
33	1		USPAT	2002/09/07 16:13
34	8	((257/704 257/706 257/707 257/713 257/718 257/720 257/675 257/728 257/779 257/783) and ((heat thermal) NEAR (spreader dissipat\$3))) and (die chip wafer) NEAR surface)) and (solder\$3 NEAR thermal\$2 NEAR conduct\$3)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/09/07 16:20
35	29	(257/704 257/706 257/707 257/713 257/718 257/720 257/675 257/728 257/779 257/783) and (solder\$3 NEAR thermal\$2 NEAR conduct\$3)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/09/07 16:24

36	4327	438/122 438/125 438/612 438/118	USPAT; US-PGPUB; EPO, JPO, IBM_TDB	2002/09/07 16:24
37	7	(438/122 438/125 438/612 438/118) and (solder\$3 NEAR thermal\$2 NEAR conduct\$3)	USPAT; US-PGPUB; EPO, JPO, IBM_TDB	2002/09/07 16:24
38	640	(438/122 438/125 438/612 438/118) and ((heat thermal) NEAR (spreader dissipat\$3))	USPAT; US-PGPUB; EPO, JPO, IBM_TDB	2002/09/07 16:25
39	7	((438/122 438/125 438/612 438/118) and (solder\$3 NEAR thermal\$2 NEAR conduct\$3)) and (die chip wafer)	USPAT; US-PGPUB; EPO, JPO, IBM_TDB	2002/09/07 16:26
40	597	((438/122 438/125 438/612 438/118) and ((heat thermal) NEAR (spreader dissipat\$3))) and (die chip wafer)	USPAT; US-PGPUB; EPO, JPO, IBM_TDB	2002/09/07 16:26
41	263	((438/122 438/125 438/612 438/118) and ((heat thermal) NEAR (spreader dissipat\$3))) and ((die chip wafer) NEAR surface)	USPAT; US-PGPUB; EPO, JPO, IBM_TDB	2002/09/07 16:26
42	10	((438/122 438/125 438/612 438/118) and ((heat thermal) NEAR (spreader dissipat\$3))) and ((die chip wafer) NEAR surface)) and (solder-wet\$4 (solder NEAR wet\$4))	USPAT; US-PGPUB; EPO, JPO, IBM_TDB	2002/09/07 16:26